



8-Bit Serial-Input/Serial or Parallel-Output Shift Register with Latched 3-State Outputs

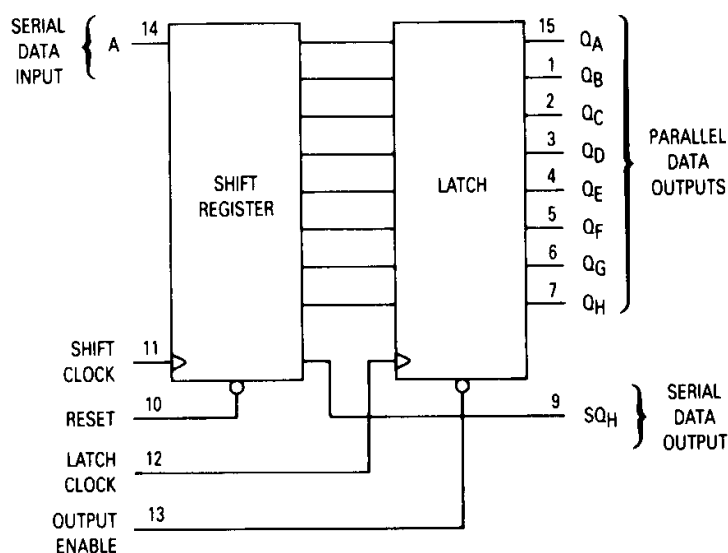
High-Performance Silicon-Gate CMOS

The HT74HC595A is identical in pinout to the LS/ALS595. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LS/ALSTTL outputs.

The HT74HC595A consists of an 8-bit shift register and an 8-bit D-type latch with three-state parallel outputs. The shift register accepts serial data and provides a serial output. The shift register also provides parallel data to the 8-bit latch. The shift register and latch have independent clock inputs. This device also has an asynchronous reset for the shift register.

- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0 μ A
- High Noise Immunity Characteristic of CMOS Devices

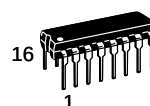
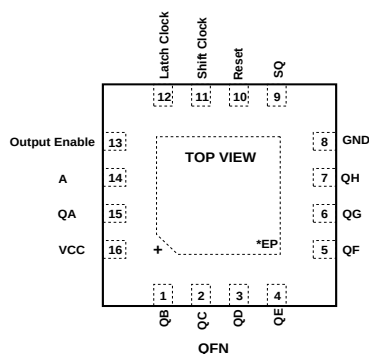
LOGIC DIAGRAM



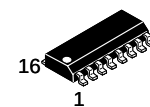
PIN 16 = V_{CC}
PIN 8 = GND

PIN ASSIGNMENT

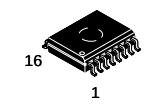
Q_B	1	16	V_{CC}
Q_C	2	15	Q_A
Q_D	3	14	A
Q_E	4	13	Output Enable
Q_F	5	12	Latch Clock
Q_G	6	11	Shift Clock
Q_H	7	10	Reset
GND	8	9	SQ



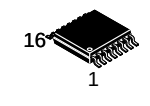
DIP16 N SUFFIX
HT74HC595ANZ



SOP16 R
SUFFIX
HT74HC595ARZ



WSOP16 W
SUFFIX
HT74HC595ARWZ



TSSOP16 T
SUFFIX
HT74HC595ARTZ



SSOP16 S
SUFFIX
HT74HC595ARSZ



QFN16-3*3 Q
SUFFIX
HT74HC595ARQZ

T_A = from -55 to 125 $^{\circ}$ C For all packages

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	-1.5 to $V_{CC} + 1.5$	V
V_{OUT}	DC Output Voltage (Referenced to GND)	-0.5 to $V_{CC} + 0.5$	V
I_{IN}	DC Input Current, per Pin	± 20	mA
I_{OUT}	DC Output Current, per Pin	± 35	mA
I_{CC}	DC Supply Current, V_{CC} and GND Pins	± 75	mA
P_D	Power Dissipation in Still Air, Plastic DIP+ SOIC Package+	750 500	mW
Tstg	Storage Temperature	-65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package)	260	°C

*Maximum Ratings are those values beyond which damage to the device may occur.
Functional operation should be restricted to the Recommended Operating Conditions.

+Derating - Plastic DIP: - 10 mW/°C from 65° to 125°C
SOIC Package: - 7 mW/°C from 65° to 125°C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	2.0	6.0	V
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Referenced to GND)	0	V_{CC}	V
T_A	Operating Temperature, All Package Types	-55	+125	°C
t_r, t_f	Input Rise and Fall Time (Figure 1)	$V_{CC} = 2.0\text{ V}$ $V_{CC} = 4.5\text{ V}$ $V_{CC} = 6.0\text{ V}$		ns
		0	1000	
		0	500	
		0	400	

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{IN} and V_{OUT} should be constrained to the range $GND \leq (V_{IN} \text{ or } V_{OUT}) \leq V_{CC}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

DC ELECTRICAL CHARACTERISTICS(Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V _{CC} V	Guaranteed Limit			Unit
				25 °C to -55°C	≤85 °C	≤125 °C	
V _{IH}	Minimum High-Level Input Voltage	V _{OUT} =0.1 V or V _{CC} -0.1 V I _{OUT} ≤ 20 μA	2.0 4.5 6.0	1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V
V _{IL}	Maximum Low - Level Input Voltage	V _{OUT} =0.1 V or V _{CC} -0.1 V I _{OUT} ≤ 20 μA	2.0 4.5 6.0	0.5 1.35 1.8	0.5 1.35 1.8	0.5 1.35 1.8	V
V _{OH}	Minimum High-Level Output Voltage, Q _A -Q _H	V _{IN} =V _{IH} or V _{IL} I _{OUT} ≤ 20 μA	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		V _{IN} =V _{IH} or V _{IL} I _{OUT} ≤ 6.0 mA I _{OUT} ≤ 7.8 mA	4.5 6.0	3.98 5.48	3.84 5.34	3.7 5.2	
V _{OL}	Maximum Low-Level Output Voltage, Q _A -Q _H	V _{IN} =V _{IH} or V _{IL} I _{OUT} ≤ 20 μA	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		V _{IN} =V _{IH} or V _{IL} I _{OUT} ≤ 6.0 mA I _{OUT} ≤ 7.8 mA	4.5 6.0	0.26 0.26	0.33 0.33	0.4 0.4	
V _{OH}	Minimum High-Level Output Voltage, S _Q _H	V _{IN} =V _{IH} or V _{IL} I _{OUT} ≤ 20 μA	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		V _{IN} =V _{IH} or V _{IL} I _{OUT} ≤ 4.0 mA I _{OUT} ≤ 5.2 mA	4.5 6.0	3.98 5.48	3.84 5.34	3.7 5.2	
V _{OL}	Maximum Low-Level Output Voltage, S _Q _H	V _{IN} =V _{IH} or V _{IL} I _{OUT} ≤ 20 μA	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		V _{IN} =V _{IH} or V _{IL} I _{OUT} ≤ 4.0 mA I _{OUT} ≤ 5.2 mA	4.5 6.0	0.26 0.26	0.33 0.33	0.4 0.4	
I _{IN}	Maximum Input Leakage Current	V _{IN} =V _{CC} or GND	6.0	±0.1	±1.0	±1.0	μA
I _{OZ}	Maximum Three-State Leakage Current, Q _A -Q _H	Output in High-Impedance State V _{IN} = V _{IL} or V _{IH} V _{IN} =V _{CC} or GND	6.0	±0.5	±5.0	±10	μA
I _{CC}	Maximum Quiescent Supply Current (per Package)	V _{IN} =V _{CC} or GND I _{OUT} =0μA	6.0	4.0	40	160	μA

AC ELECTRICAL CHARACTERISTICS($C_L=50\text{pF}$, Input $t_r=t_f=6.0\text{ ns}$)

Symbol	Parameter	V _{CC}	Guaranteed Limit			Unit
		V	25 °C to -55°C	≤85 °C	≤125 °C	
f _{max}	Minimum Clock Frequency (50% Duty Cycle) (Figures 1 and 7)	2.0 4.5 6.0	6.0 30 35	4.8 24 28	4.0 20 24	MHz
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Shift Clock to SQ _H (Figures 1 and 7)	2.0 4.5 6.0	140 28 24	175 35 30	210 42 36	ns
t _{PHL}	Maximum Propagation Delay , Reset to SQ _H (Figures 2 and 7)	2.0 4.5 6.0	145 29 25	180 36 31	220 44 38	ns
t _{PLH} , t _{PHL}	Maximum Propagation Delay , Latch Clock to Q _A -Q _H (Figures 3 and 7)	2.0 4.5 6.0	140 28 24	175 35 30	210 42 36	ns
t _{PLZ} , t _{PHZ}	Maximum Propagation Delay , Output Enable to Q _A -Q _H (Figures 4 and 8)	2.0 4.5 6.0	150 30 26	190 38 33	225 45 38	ns
t _{PZL} , t _{PZH}	Maximum Propagation Delay , Output Enable to Q _A -Q _H (Figures 4 and 8)	2.0 4.5 6.0	135 27 23	170 34 29	205 41 35	ns
t _{TLH} , t _{THL}	Maximum Output Transition Time, Q _A -Q _H (Figures 3 and 7)	2.0 4.5 6.0	60 12 10	75 15 13	90 18 15	ns
t _{TLH} , t _{THL}	Maximum Output Transition Time, SQ _H (Figures 1 and 7)	2.0 4.5 6.0	75 15 13	95 19 16	110 22 19	ns
C _{IN}	Maximum Input Capacitance	-	10	10	10	pF
C _{OUT}	Maximum Three-State Output Capacitance (Output in High-Impedance State), Q _A -Q _H	-	15	15	15	pF

C _{PD}	Power Dissipation Capacitance (Per Package)	Typical @25°C, V _{CC} =5.0 V			pF
	Used to determine the no-load dynamic power consumption: P _D =C _{PD} V _{CC} ² f+I _{CC} V _{CC}	300			

TIMING REQUIREMENTS($C_L=50\text{pF}$, Input $t_r=t_f=6.0\text{ ns}$)

Symbol	Parameter	V _{CC} V	Guaranteed Limit			Unit
			25 °C to -55°C	≤85°C	≤125°C	
t _{su}	Minimum Setup Time, Serial Data Input A to Shift Clock (Figure 5)	2.0	50	65	75	ns
		4.5	10	13	15	
		6.0	9	11	13	
t _{su}	Minimum Setup Time, Shift Clock to Latch Clock (Figure 6)	2.0	75	95	110	ns
		4.5	15	19	22	
		6.0	13	16	19	
t _h	Minimum Hold Time, Shift Clock to Serial Data Input A (Figure 5)	2.0	5	5	5	ns
		4.5	5	5	5	
		6.0	5	5	5	
t _{rec}	Minimum Recovery Time, Reset Inactive to Shift Clock (Figure 2)	2.0	50	65	75	ns
		4.5	10	13	15	
		6.0	9	11	13	
t _w	Minimum Pulse Width, Reset (Figure 2)	2.0	60	75	90	ns
		4.5	12	15	18	
		6.0	10	13	15	
t _w	Minimum Pulse Width, Shift Clock (Figure 1)	2.0	50	65	75	ns
		4.5	10	13	15	
		6.0	9	11	13	
t _w	Minimum Pulse Width, Latch Clock (Figure 6)	2.0	50	65	75	ns
		4.5	10	13	15	
		6.0	9	11	13	
t _r , t _f	Maximum Input Rise and Fall Times (Figure 1)	2.0	1000	1000	1000	ns
		4.5	500	500	500	
		6.0	400	400	400	

FUNCTION TABLE

Operation	Inputs					Resulting Function			
	Reset	Serial Input A	Shift Clock	Latch Clock	Output Enable	Shift Register Contents	Latch Register Contents	Serial Output SQ _H	Parallel Outputs Q _A -Q _H
Reset shift register	L	X	X		L	L	U	L	U
Shift data into shift register	H	D			L	D → SR _A SR _N → SR _{N+1}	U	SR _G → SR _H	U
Shift register remains unchanged	H	X			L	U	U	U	U
Transfer shift register contents to latch register	H	X			L	U	SR _N → LR _N	U	SR _N
Latch register remains unchanged	X	X	X		L	*	U	*	U
Enable parallel outputs	X	X	X	X	L	*	**	*	Enabled
Force outputs into high-impedance state	X	X	X	X	H	*	**	*	Z

SR = shift register contents

X = don't care

LR = latch register contents

Z = high impedance

D = data (L,H) logic level

* = depends on Reset and Shift Clock inputs

U = remains unchanged

** = depends on Latch Clock input

PIN DESCRIPTIONS

INPUTS:

A - Serial Data Input. The data on this pin is shifted into the 8-bit serial shift register.

CONTROL INPUTS:

Shift Clock - Shift Register Clock Input. A low-to-high transition on this input causes the data at the Serial Input pin to be shifted into the 8-bit shift register.

Reset - Active-low, Asynchronous, Shift Register Reset Input. A low on this pin resets the shift register portion of this device only. The 8-bit latch is not affected.

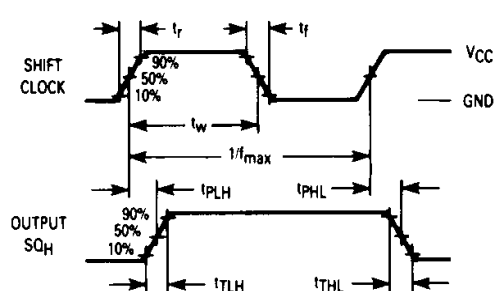
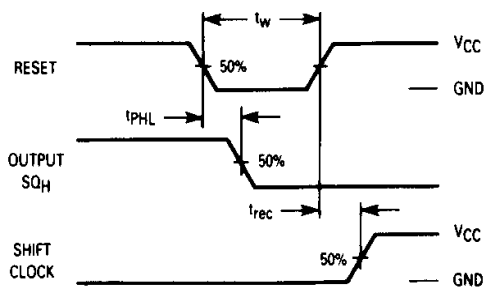
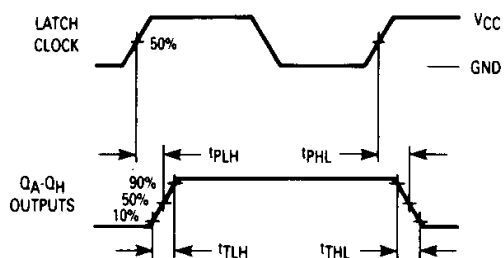
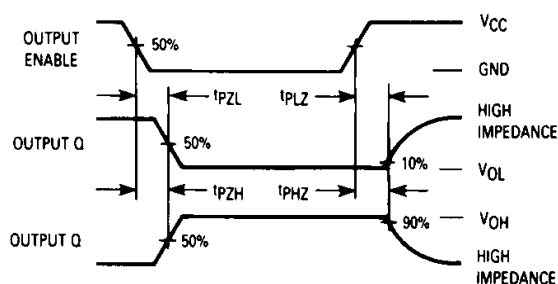
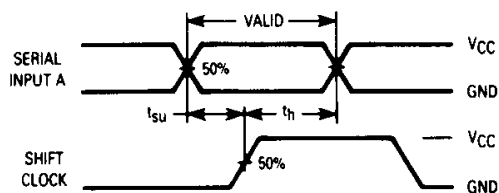
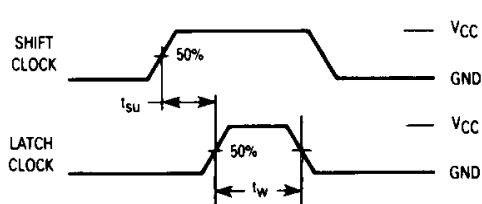
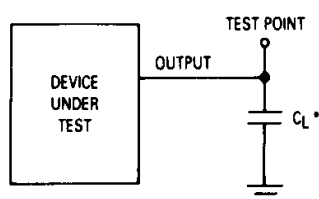
Latch Clock - Storage Latch Clock Input. A low-to-high transition on this input latches the shift register data.

Output Enable - Active-Low Output Enable. A low on this input allows the data from the latches to be presented at the outputs. A high on this input forces the outputs (Q_A-Q_H) into the high-impedance state. The serial output is not affected by this control unit.

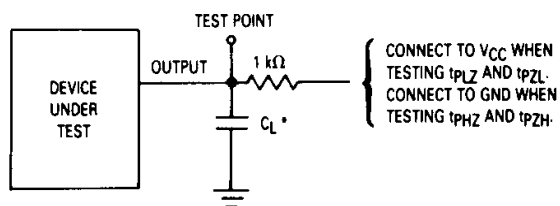
OUTPUTS:

Q_A-Q_H - Noninverted, 3-state, latch outputs.

SQ_H - Noninverted, Serial Data Output. This is the output of the eighth stage of the 8-bit shift register. This output does not have three-state capability.


Figure 1. Switching Waveforms

Figure 2. Switching Waveforms

Figure 3. Switching Waveforms

Figure 4. Switching Waveforms

Figure 5. Switching Waveforms

Figure 6. Switching Waveforms


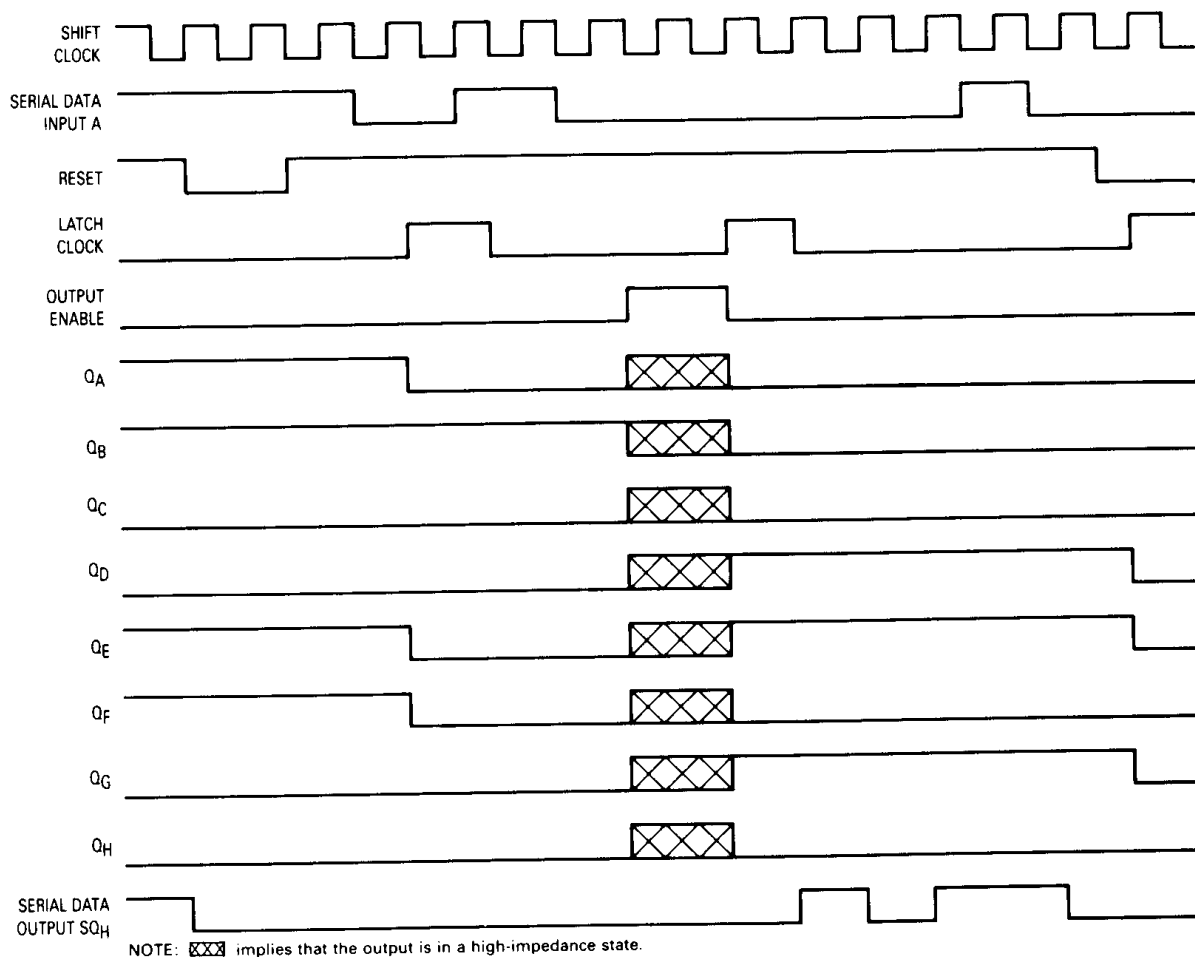
*Includes all probe and jig capacitance.

Figure 7. Test Circuit


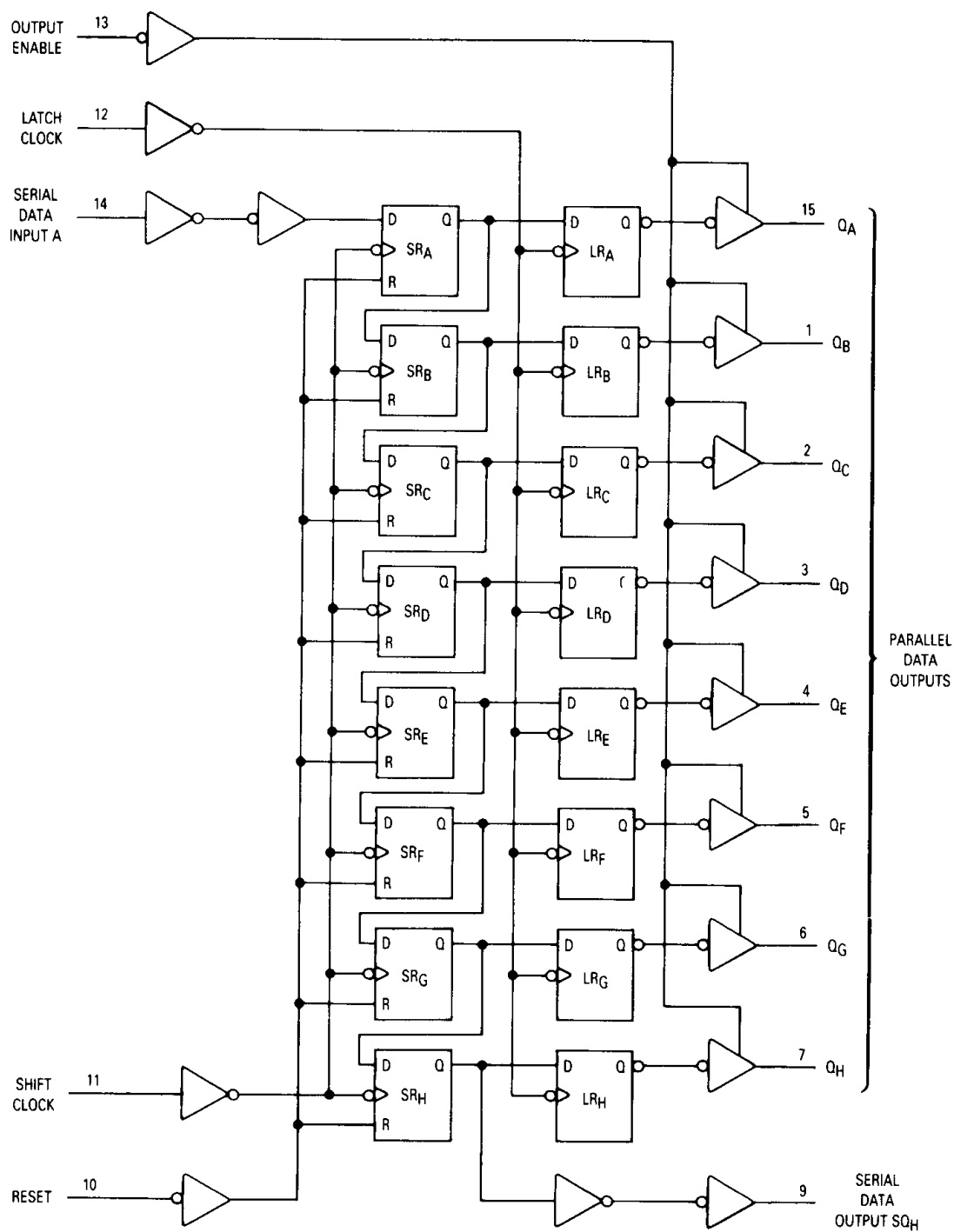
*Includes all probe and jig capacitance.

Figure 8. Test Circuit

TIMING DIAGRAM

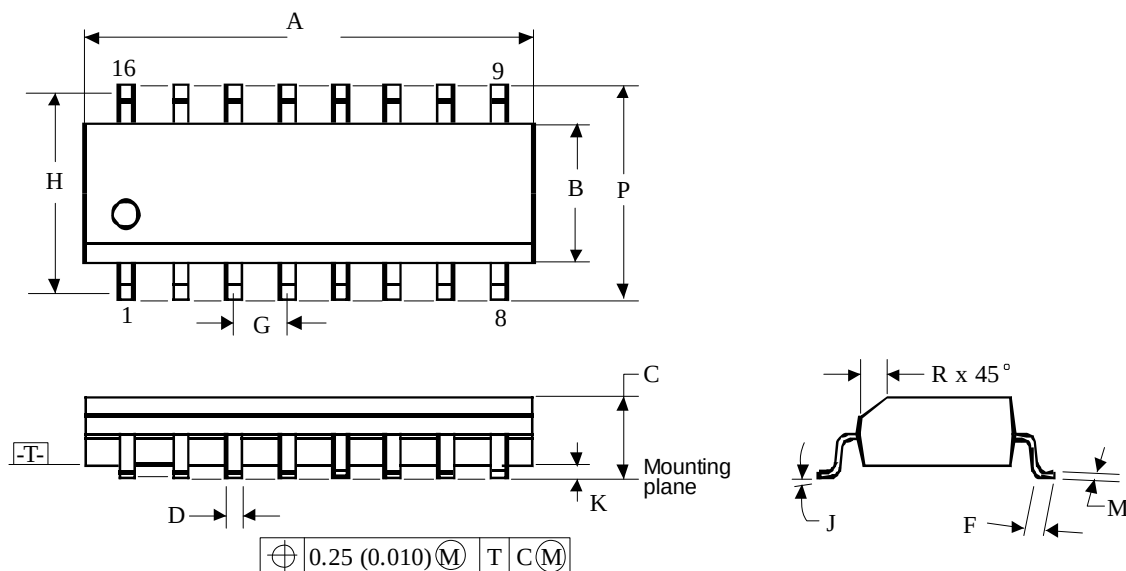


EXPANDED LOGIC DIAGRAM



Package Dimensions

SOP16



Note:

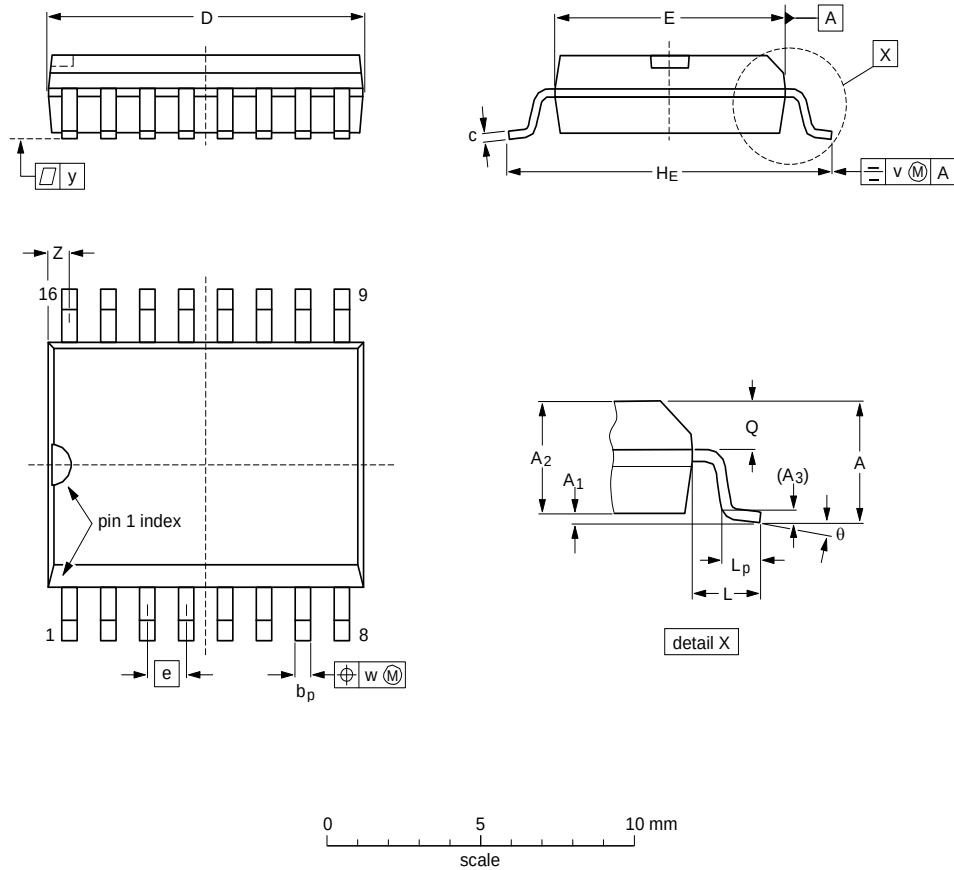
1. Dimensional sizes A and B are preset without consideration of fin and the metal bulges.
2. Availability of the fin and the metal bulges for A – up to 0.15 mm (0.006) per side; for B – up to 0.25 mm (0.010) per side.

Identifi- cation

Sizes, mm

	MIN	MAX
A	9.80	10.0
B	3.80	4.00
C	1.35	1.75
D	0.33	0.51
F	0.40	1.27
G	1.27	
H	5.72	
J	0°	8°
K	0.10	0.25
M	0.19	0.25
P	5.80	6.20
R	0.25	0.50

WSOP16: plastic small outline package; 16 leads; body width 7.5 mm



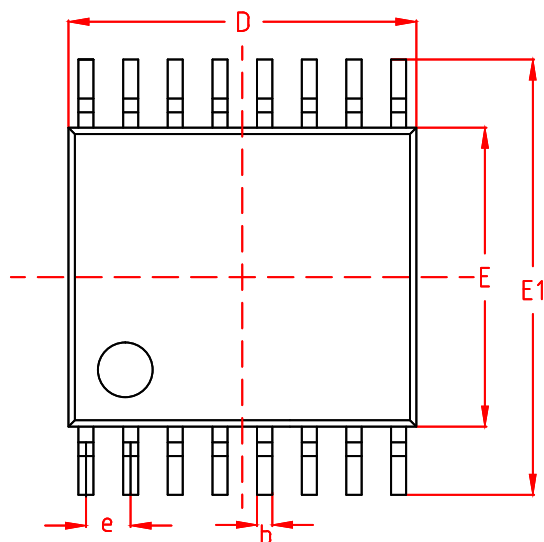
DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A _{max.}	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	10.5 10.1	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.41 0.40	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

TSSOP16: plastic small outline package; 16 leads; body width 4.4 mm

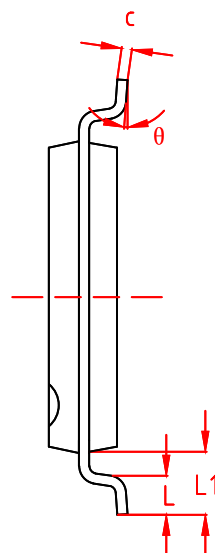
TOP VIEW

正视图



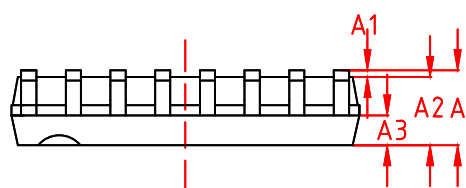
SIDE VIEW

侧视图



SIDE VIEW

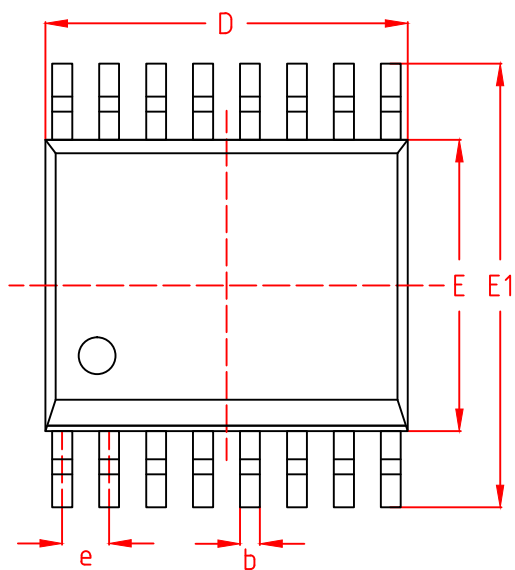
侧视图



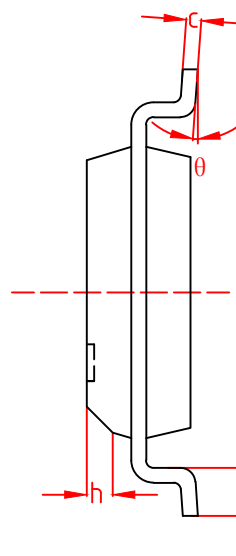
机械尺寸/mm Dimensions			
字符 SYMBOL	最小值 MIN	典型值 NOMINAL	最大值 MAX
A	-	-	1.20
A1	0.05	-	0.15
A2	0.90	1.00	1.05
A3	0.39	0.44	0.49
b	0.20	-	0.28
c	0.13	-	0.17
D	4.90	5.00	5.10
E	4.30	4.40	4.50
E1	6.20	6.40	6.60
e	0.65 BSC		
L1	1.00REF		
L	0.45	0.60	0.75
θ	0°	-	8°

SSOP16: plastic small outline package; 16 leads; body width 3.9 mm

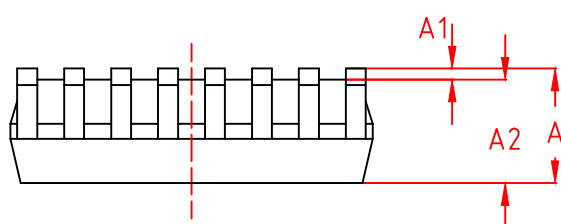
TOP VIEW
正视图



SIDE VIEW
侧视图



SIDE VIEW
侧视图

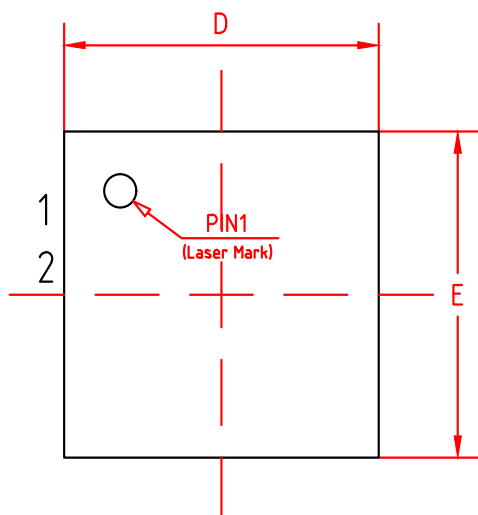


机械尺寸/mm Dimensions			
字符 SYMBOL	最小值 MIN	典型值 NOMINAL	最大值 MAX
A	—	—	1.75
A1	0.10	0.15	0.25
A2	1.35	1.45	1.55
b	0.23	—	0.31
c	0.19	—	0.25
D	4.80	4.90	5.00
E	3.80	3.90	4.00
E1	5.80	6.00	6.20
e	0.635 BSC		
h	0.30	—	0.50
L	0.50	—	0.80
θ	0°	—	8°

QFN16-3x3x0.75-P0.5

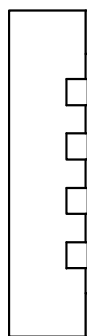
TOP VIEW

正视图



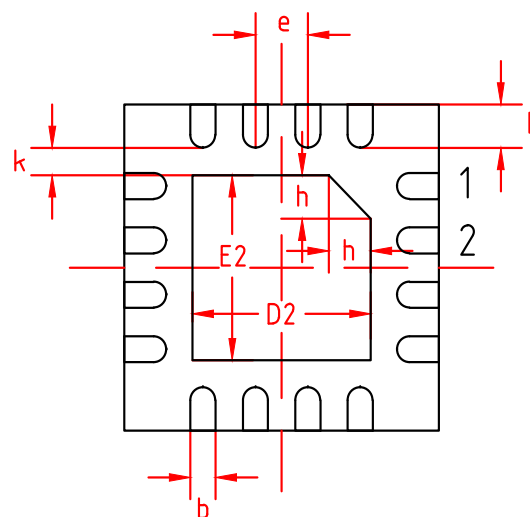
SIDE VIEW

侧视图



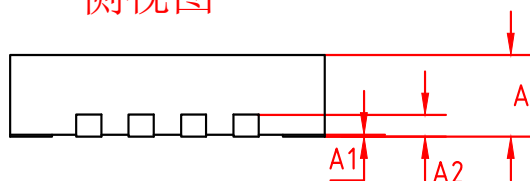
BOTTOM VIEW

背视图



SIDE VIEW

侧视图



机械尺寸/mm

字符 SYMBOL	最小值 MIN	典型值 NOMINAL	最大值 MAX
A	0.70	0.75	0.80
A1	0	0.02	0.05
A2	0.203 REF		
b	0.18	0.24	0.30
D	2.90	3.00	3.10
E	2.90	3.00	3.10
e	0.50 BSC		
D2	1.6	1.7	1.8
E2	1.6	1.7	1.8
K	0.20	0.25	0.30
L	0.30	0.40	0.50
h	0.35	0.40	0.45